Advance Product Change Notification

201405007A

Issue Date: 15-Jun-2014

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Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire and release of 2nd source mold compound in DFN2020MD-6 (SOT1220)

Details of this Planned Change

Scheduled changes affect product types in DFN2020MD-6 (SOT1220) package only.
(1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons.
(2) The wire diameter of the gate wire will be changed from 23µm to 50µm.
(3) A second source mold compound supplier will be introduced.

Old product: Wire material is Au (with currently used mold compound suppliers), gate wire diameter is 23µm.
Changed product: Wire material is Cu or Au (with currently used first and new second source mold compound supplier), gate wire diameter is 23µm (gold wire) or 50µm (copper wire).

The design and materials of all other components will remain unchanged:
Die, die attach and lead frame.
Reliability qualification and full electrical characterization over temperature will be performed. For details please see the Self Qualification Plan.
No change on thermal behavior or mechanical dimensions.
Electrical parameters will remain unchanged (in specification and with the same distribution).

Why do we Plan this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages.

Copper wire shows enhanced mechanical properties.
(2) To streamline the production process, all wires in the package will get the same diameter.
(3) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in DFN2020MD-6 (SOT1220) package.
The second source supplier is already well established for NXP semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Samples can be ordered now and will be shipped latest after FPCN issue date.

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Final PCN is planned to be issued on: 05-Aug-2014.
Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Jul-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

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